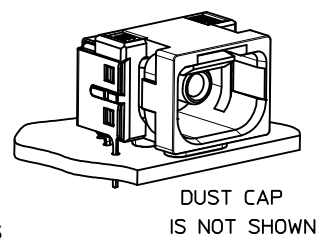
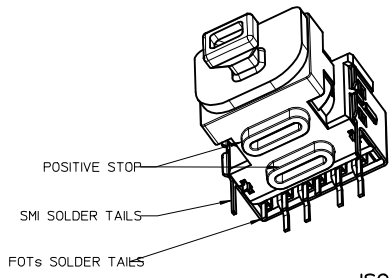
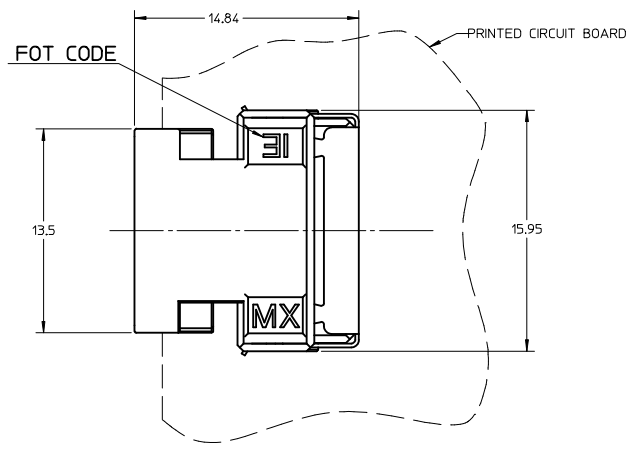
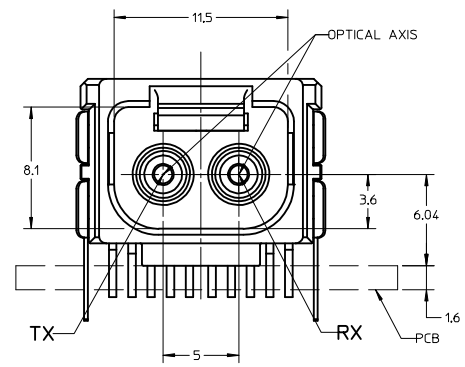
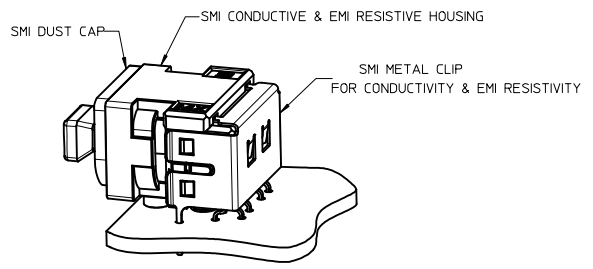


SMI/SMT TRANSCEIVER ASSEMBLY P/N	FOT's TYPE	FOT CODE
1061083100	10/100 ETHERNET	EL
1061084100	INDUSTRIAL DATA LINK	ID
1061083101	10/100 ETHERNET	EL
1061084110	INDUSTRIAL DATA LINK	ID

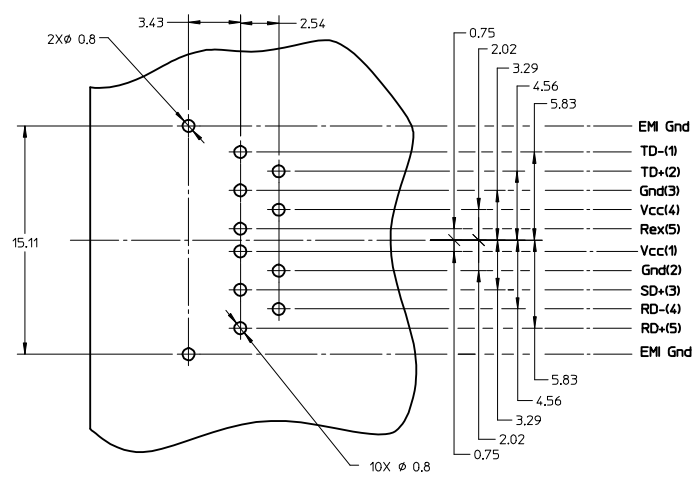
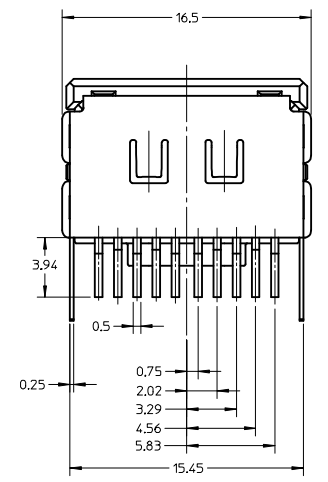
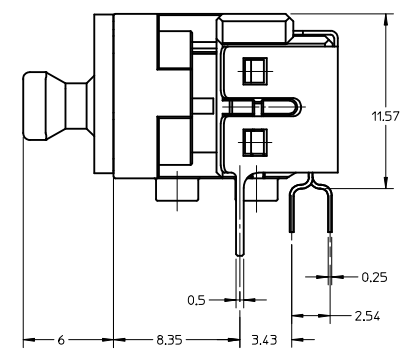


ISOMETRIC VIEWS
SCALE 2.5:1

DUST CAP NOT SHOWN



SMI TRANSCEIVER ASSEMBLY
MOUNTED ON THE PCB
DUST CAP NOT SHOWN



RECOMMENDED PCB LAYOUT
DIMENSIONS TOLERANCE: ±0.1mm

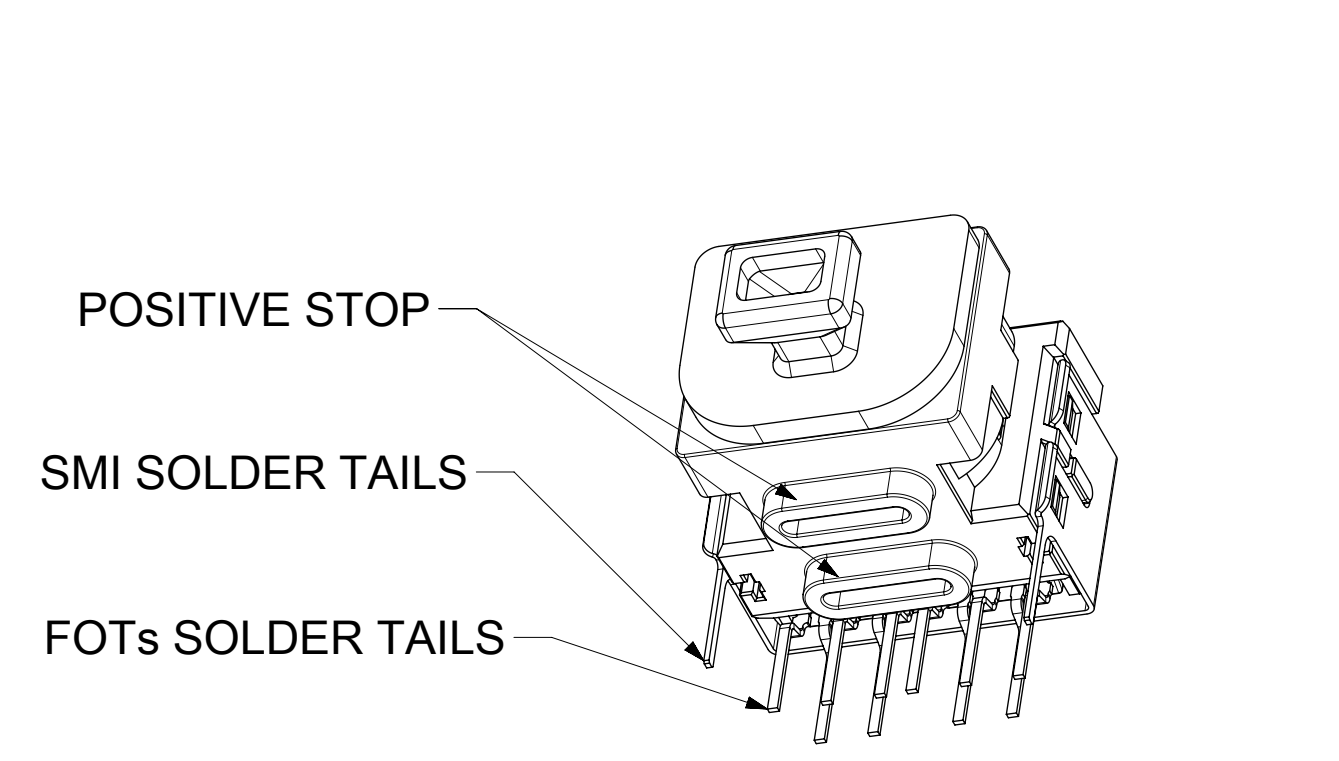
- EMI Gnd
- TD-(1)
- TD+(2)
- Gnd(3)
- Vcc(4)
- Rex(5)
- Vcc(1)
- Gnd(2)
- SD+(3)
- RD-(4)
- RD+(5)
- EMI Gnd

NOTES:

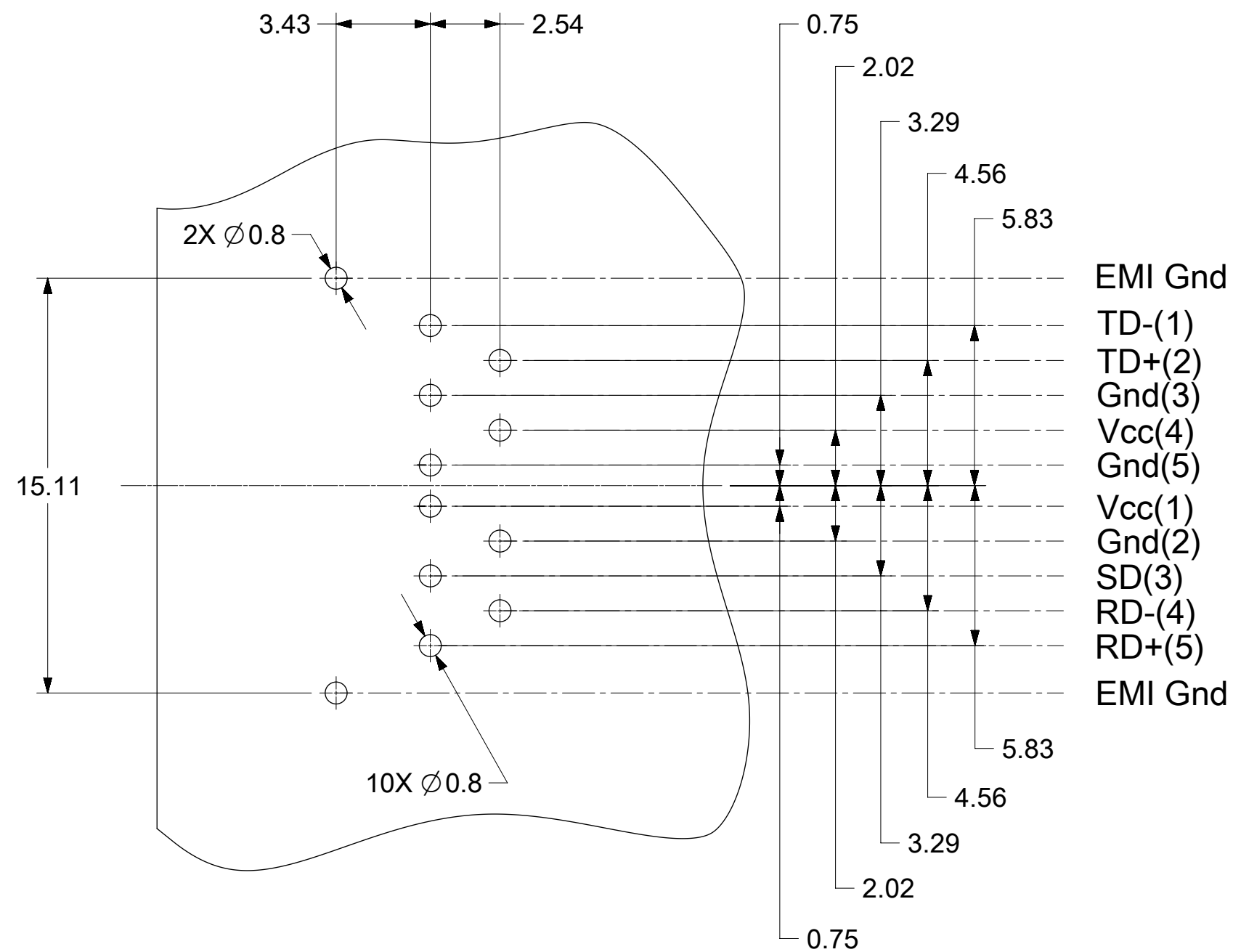
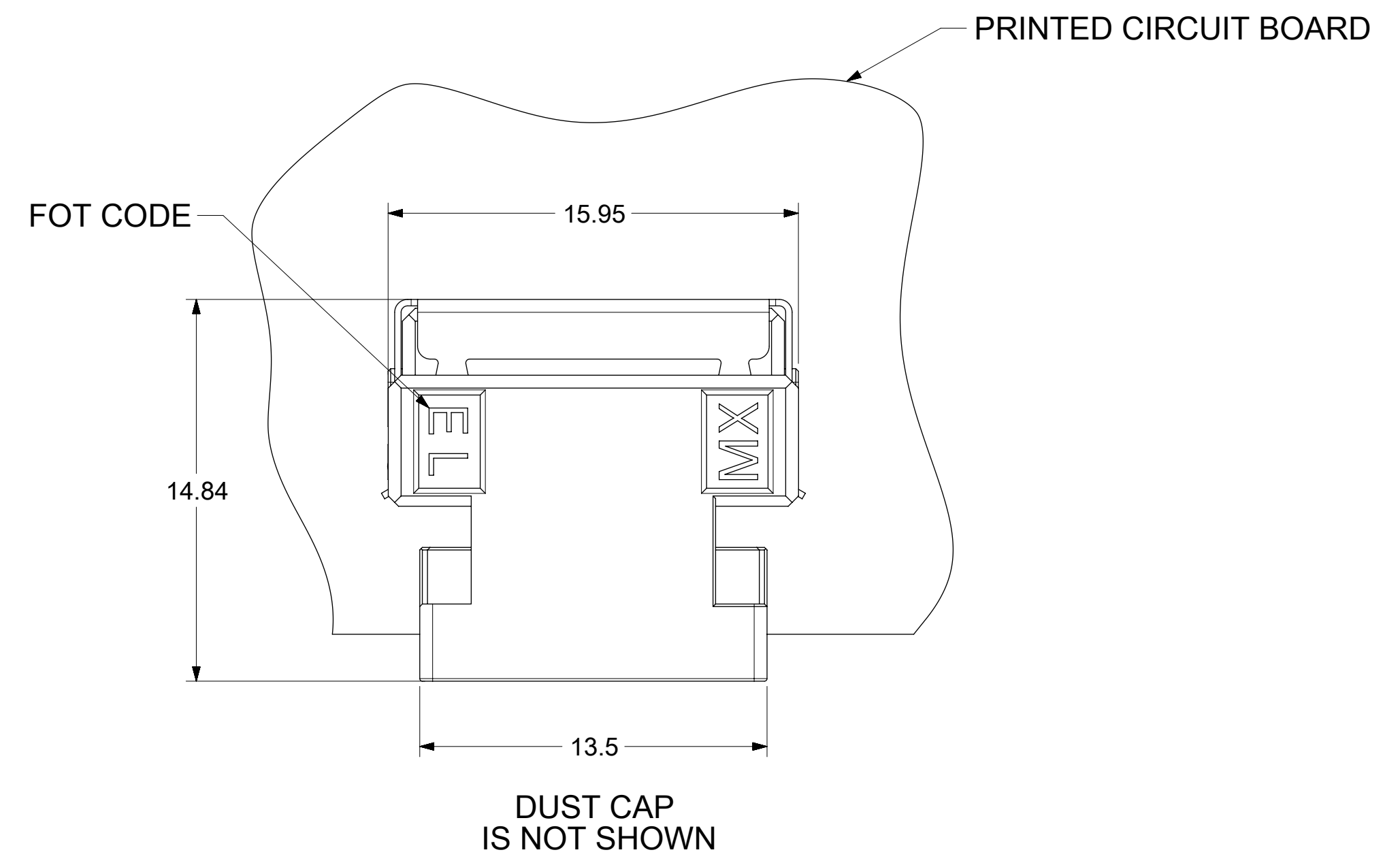
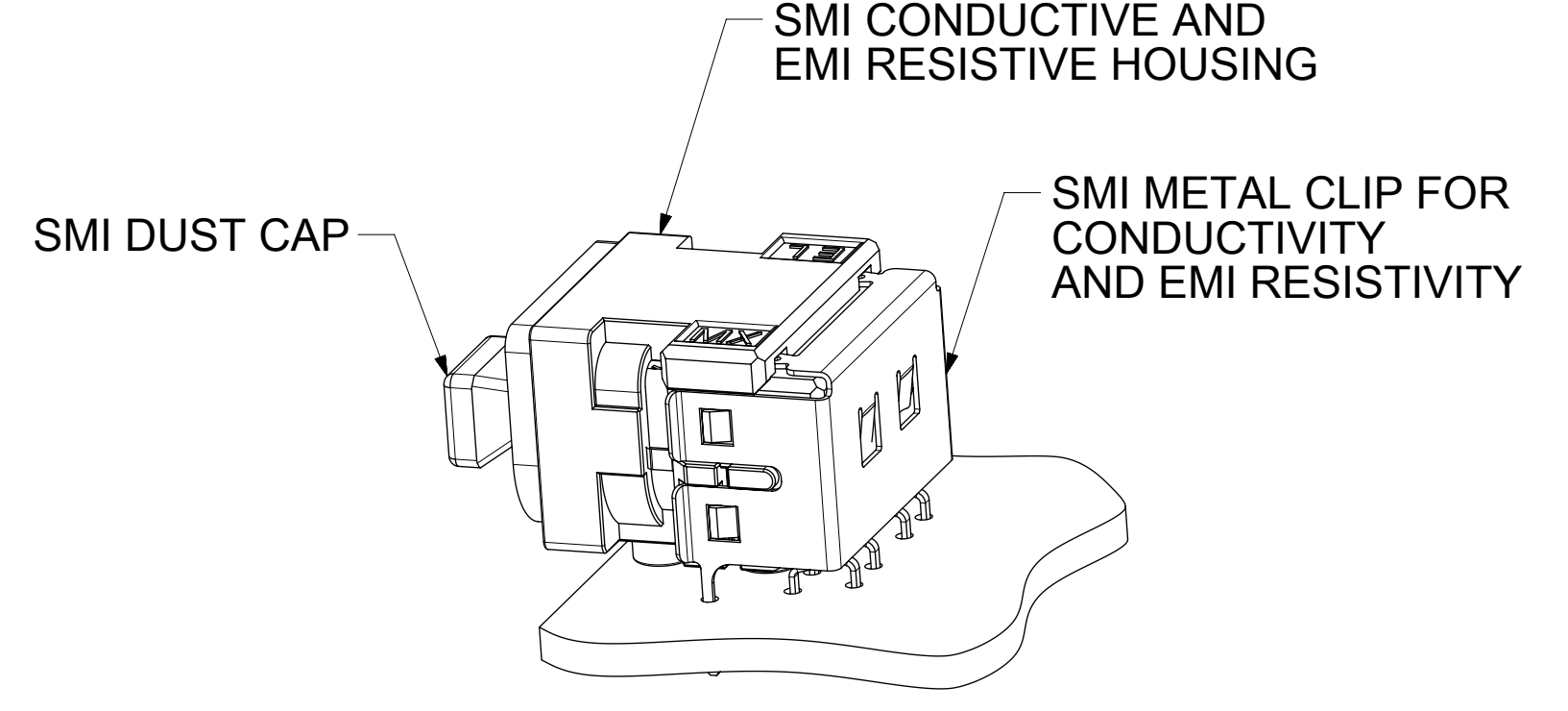
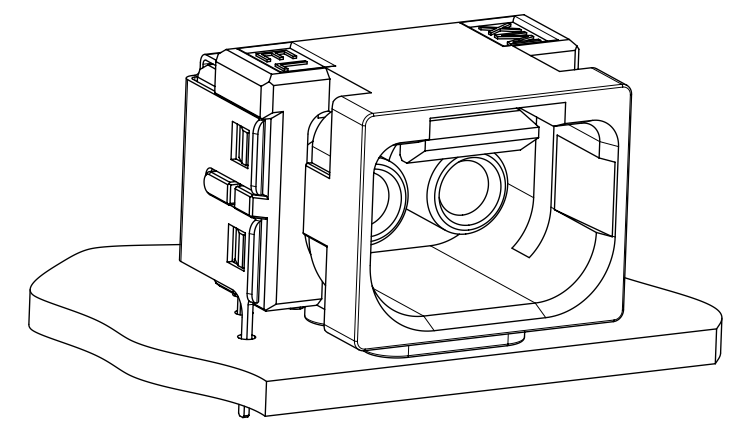
- ALL DIMENSIONS ARE FOR REFERENCE ONLY EXCEPT FOR RECOMMENDED PCB LAYOUT.
- ATTACHMENT OF THIS COMPONENT TO THE PCB VIA HOT BAR/LASER OR IR SOLDERING. RE-FLOW OVEN SOLDERING IS NOT APPROVED AT THIS TIME.

ENTER DESCRIPTION EC NO: MF2014-0532 DRWNS:SBJANIC 2014/02/20 CHKD: APPR: IGJMIN 2014/02/21	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY BG	DATE 09/12/06	TITLE SMI TRANSCEIVER ASSEMBLY THROUGH- HOLE SOLDERING			
4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± --- ± ---	1 PLACE ± --- ± ---	CHECKED BY SE	DATE 9/15/06				
0 PLACE ± ±	ANGULAR ±1/2°		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-106108-X100	SHEET NO. 1 OF 1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

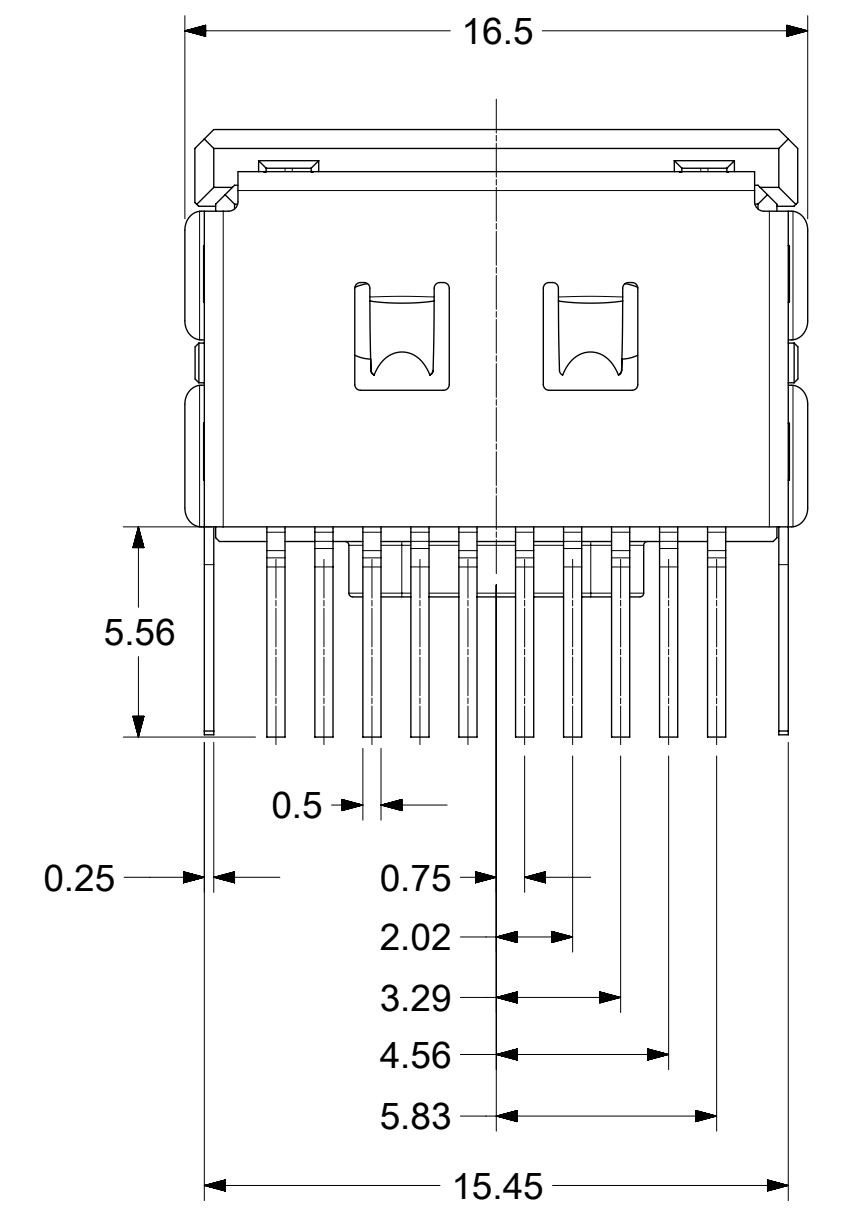
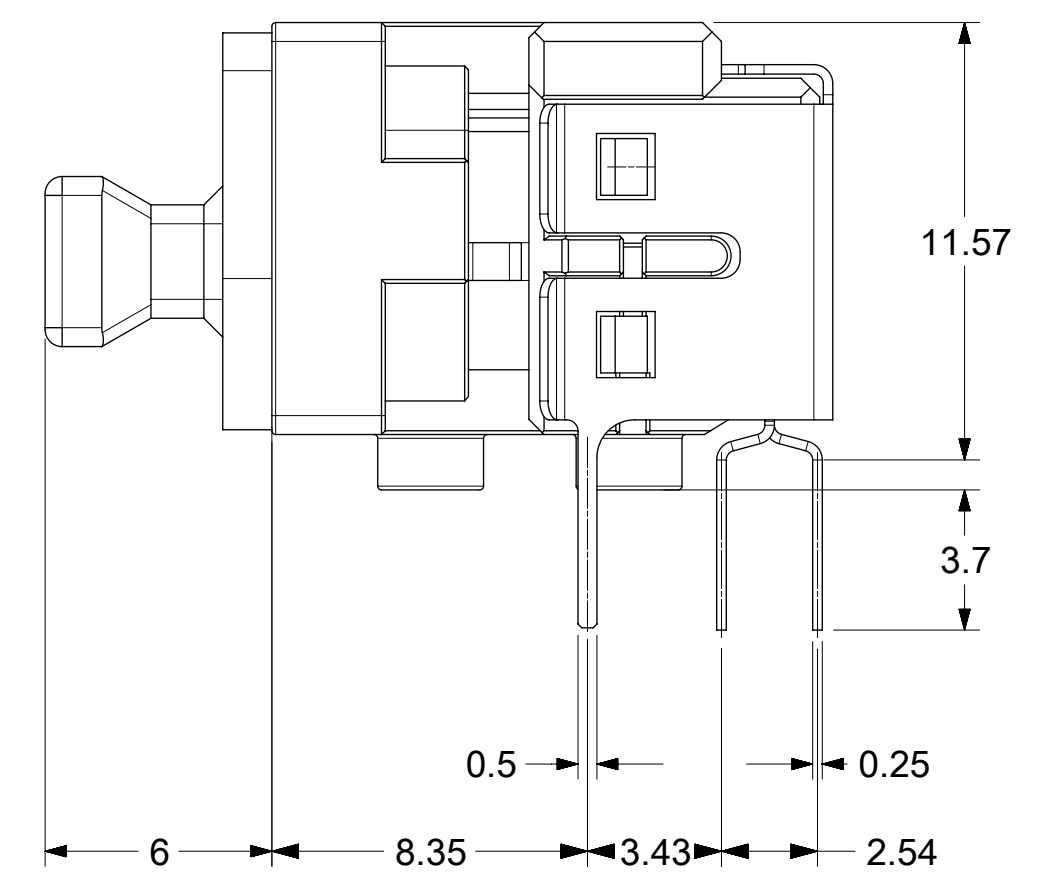
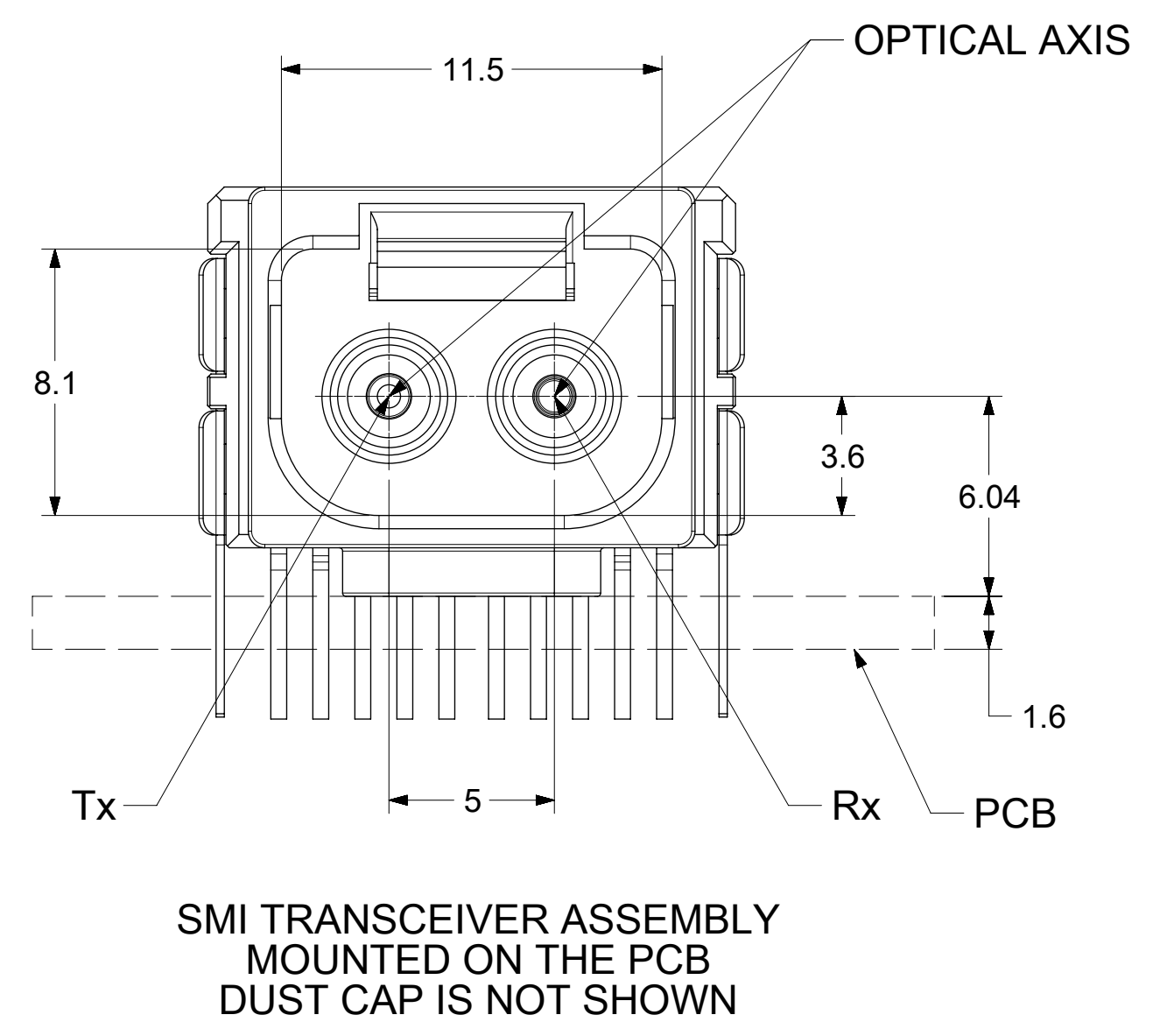
SMI TRANSCEIVER ASSEMBLY P/N	FOT's TYPE	FOT CODE
1061083100	ETHERNET 10/100	EL
1061084100	INDUSTRIAL DATA LINK	ID



ISOMETRIC VIEWS
SCALE 3:1



RECOMMENDED PCB LAYOUT
DIMENSIONS TOLERANCE: ±0.1mm



- NOTES:
1. ALL DIMENSIONS ARE FOR REFERENCE ONLY EXCEPT FOR RECOMMENDED PCB LAYOUT.
 2. SMI TH TRANSCEIVERS MAY BE SOLDERED TO MAX 260°, MAX 10s, ONE TIME ONLY, AT LEAST 2.20mm AWAY FROM LEAD ROOT. RE-FLOW OVEN SOLDERING IS NOT APPROVED AT THIS TIME. FOR MORE DETAILS SEE DATASHEET.

QUALITY SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		DIMENSION UNITS		SCALE	molex®			
▽ = 0	2016/07/12	2016/08/23	GENERAL TOLERANCES (UNLESS SPECIFIED)	MM	5:1	SMI TRANSCEIVER ASSEMBLY TH SOLDERING			
▽ = 0	EC NO: 107440 DRWN: SBOJANIC CHKD: IGUMIN REV APPR: IGUMIN	2016/08/23	ANGULAR TOL ± °	DRWN BY	DATE	PRODUCT CUSTOMER DRAWING			
▽ = 0			4 PLACES ±	SBOJANIC	2016/07/12	SERIES MATERIAL NUMBER CUSTOMER			
▽ = 0			3 PLACES ±	CHKD BY	DATE	106108	SEE TABLE		
▽ = 0			2 PLACES ±	APPR BY	DATE	1061083100	PSD	000	1 OF 1
▽ = 0			1 PLACE ±	IGUMIN	2016/08/23	DOCUMENT NUMBER DOC TYPE DOC PART SHEET NUMBER			
▽ = 0	0 PLACES ±	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		D	THIRD ANGLE PROJECTION				